



Community Member Monthly Highlights — November – December 1, 2022

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[From Different Dimensions](#)

Dec 01, 2022 · By Trine Pierik · [ACM Research](#), [ASE](#), [Brewer Science](#), [ERS](#), [EV Group](#), [Evatec](#), [KLA](#), [Lam Research](#), [NHanced Semiconductors](#), [Onto Innovation](#), [Plan Optik](#), [Plasma-Therm](#), [SEMI](#), [siemens](#), [TEL](#), [Veeco](#)



NOVEMBER

MEMBER HIGHLIGHTS

Onto Innovation announced the completion of a newly constructed cleanroom manufacturing area on site in Bloomington. Equipped with 20 new bays, the manufacturing floor will initially be used to build Onto's edge and backside inspection modules, its probe card test and analysis systems, and its wafer handling modules.

NHanced Semiconductors will invest more than \$236 million to build and equip a 100,000-square-foot fabrication facility built specifically for advanced packaging at the new \$84 million microelectronics campus at WestGate@Crane Technology Park in Odon. The company says it will create up to 413 jobs by the end of 2028, and the positions should offer average salaries higher than 250% of the Daviess County average.

Veeco appointed Dr. Lena Nicolaidis to its Board of Directors.

SEMI announced 65 founding members of the Semiconductor Climate Consortium, which aims to accelerate reduction of greenhouse gas emissions across the semiconductor value chain, that include **ASE**, **KLA**, **Lam Research**, **TEL**, and **Brewer Science**.

Siemens Digital Industries Software added scalable, on-demand, high performance simulation capabilities to Siemens Xcelerator as a Service (XaaS) with the launch of Simcenter Cloud HPC software.

Plan Optik developed a solution to create or refine products for 3D-Integration, 5G or other connectivity and high frequency applications with its new “Advanced Connectivity Technology (ACT)

ASE announced the industry’s first Fan-Out Chip on Substrate Chip First (FOCoS-CF) with encapsulant-separated redistribution layer (RDL) and Chip Last (FOCoS-CL) semiconductor packaging solution that elevates the performance for High Performance Computing (HPC), under the ASE VIPack™ platform.

ASE achieved a milestone by breaking ground on a new chip assembly and test facility in Penang, Malaysia.

EV Group launched the redesigned EVG150 automated resist processing system, which provides greatly improved throughput and many additional features to enable high-performance spin/spray coating and development processes in a smaller-form-factor, universal platform. The EVG150 is slated for its first delivery to Silicon Austria Labs (SAL).

Dr. Srikanth Kommu, executive vice president and chief operating officer at **Brewer Science**, is one of three members elected to join the SEMI North America Advisory Board. The Board provides guidance on SEMI Americas programs designed to advance the business interests of member companies and address significant challenges in the electronics manufacturing and design supply chain.

Following a long history of partnership between **EV Group** and The Korea National NanoFab Center (NNFC), both companies have signed a memorandum of understanding (MOU) on cooperation in the fields of nanotechnology and Internet of Things (IoT) sensors.

Neeraj Khanna, Vice President of Semiconductor Process Control at **KLA**, was appointed to the **SEMI** North America Advisory Board.

ERS electronic upgraded its Warpage Adjustment Tool (WAT330), to include powerful capabilities for warpage measurement and correction. It offers no-compromise warpage reduction performance for high volume manufacturing of fan-out packages.

Lam Research acquired SEMSYSCO to advance chip packaging. The acquisition of SEMSYSCO broadens Lam’s packaging offerings, bringing a portfolio of innovative cleaning and plating capabilities for chiplet-to-chiplet or chiplet-to-substrate heterogeneous integration.

ACM Research’s first MLO-capable Ultra C pr tool has been qualified and released to mass production at a power semiconductor manufacturer in China.

Plasma-Therm announced its Grenoble location will serve as regional headquarters to support customers located in central Europe, Middle East and North Africa markets focused on developing power, wireless, memory, sensor and MEMS, and other advanced microelectronic devices.

Hiring

Evatec: is hiring an application engineer for its optoelectronics business unit. Click [here](#) for more information about the role and how to apply.

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